

In the Claims:

Claims 1 - 17 (canceled).

Claim 18 (original): An electronic package, comprising:

a substrate having at least two electrical contacts thereon; and

a passive SMD having at least two electrical contacts respectively bonded by a solder connection to the said at least two electrical contacts on said substrate, said passive SMD encapsulated by a resin such that the space between said passive SMD and said substrate is filled with said resin and said resin forms fillets around said passive SMD solder connection.

Claim 19 (original): The package as set forth in Claim 18 wherein said passive SMD is a capacitor device having two electrical contacts with each contact having more than one contact surface and with the said solder connection for each electrical contact in contact with more than one contact surface.

Claim 20 (original): The package as set forth in Claim 19 wherein said resin is formed from an epoxy-based flux encapsulant with flux combined into a one part epoxy system.

Claim 21 (new): An electronic package, comprising:

a substrate having at least two electrical contacts thereon; and

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a passive SMD having at least two electrical contacts each having at least a lower electrical contact portion and an upper electrical contact portion with at least said lower electrical contact portion of said at least two electrical contacts of said passive SMD respectively positioned toward said at least two electrical contacts of said substrate and with said at least said lower electrical contact portion and said upper electrical contact portion of said at least two electrical contacts each respectively bonded by a solder connection to the said at least two electrical contacts on said substrate, said passive SMD encapsulated by a resin such that the space between said passive SMD and said substrate is filled with said resin and with said resin further forming fillets around each said passive SMD solder connection.

Claim 22 (new): The package as set forth in Claim 21 wherein said resin is formed from an epoxy-based flux encapsulant with flux combined into a one part epoxy system.

Claim 23 (new): The package as set forth in Claim 22 wherein said passive SMD is a capacitor device having two electrical contacts with each contact having more than one contact surface and with the said solder connection for each electrical contact in contact with more than one contact surface.

Claim 24 (new): The package as set forth in Claim 23 wherein the said two electrical contacts of said capacitor device each having more than one contact surface includes one contact surface which is generally annular and includes said lower electrical

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contact portion and said upper electrical contact portion and further includes another contact surface which generally caps said surface which is generally annular.